

This cross-sectional view shows a multi-layered assembly. At the base is a thick substrate (4). Above it is a layer (6) containing three parallel conductive traces (9). A central layer (1) is positioned above the traces, with two rectangular regions (15) on either side. These regions are connected to the traces by curved lines (8). On the right side, a component (3) is shown with a top layer (7) and a bottom layer (25). It is connected to the traces (9) via conductive paths (35a and 35b). A curved line (2) is also shown on the right side of the assembly.

FIG. 2 (a)

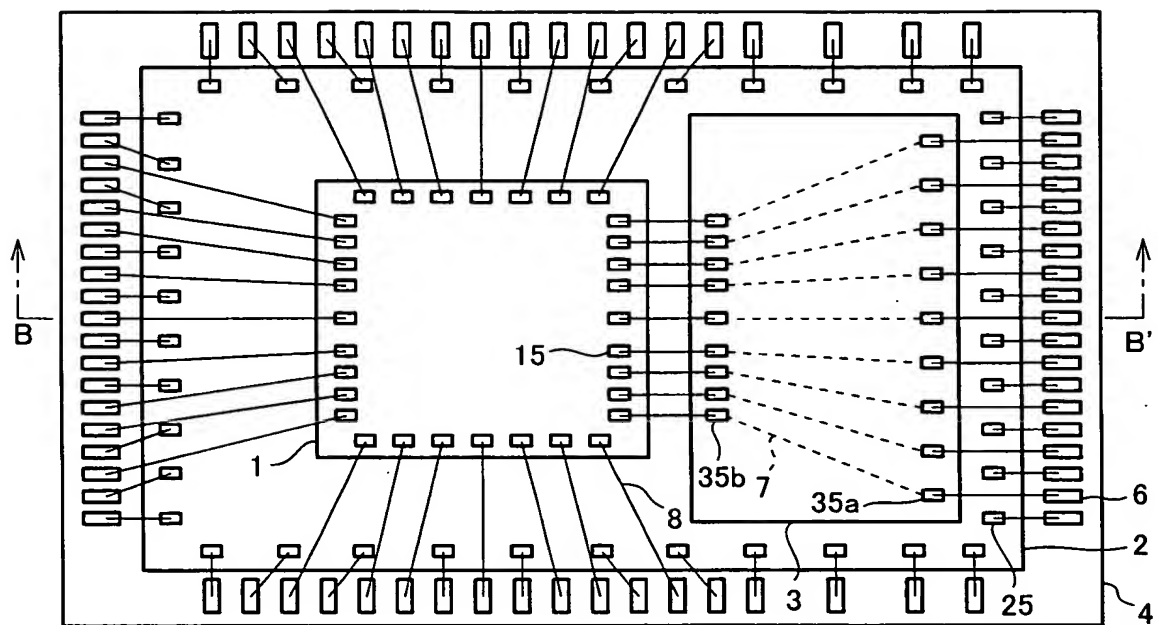


FIG. 2 (b)

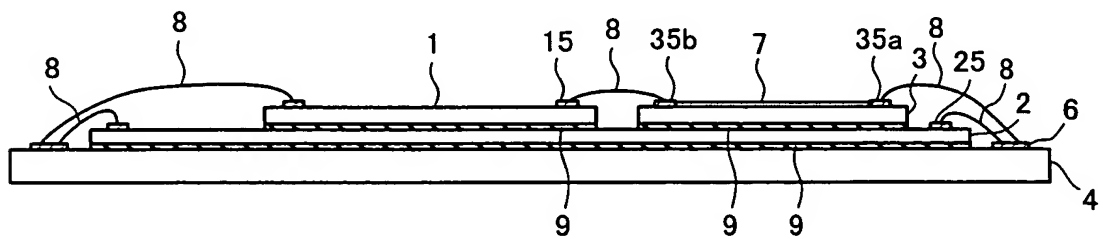
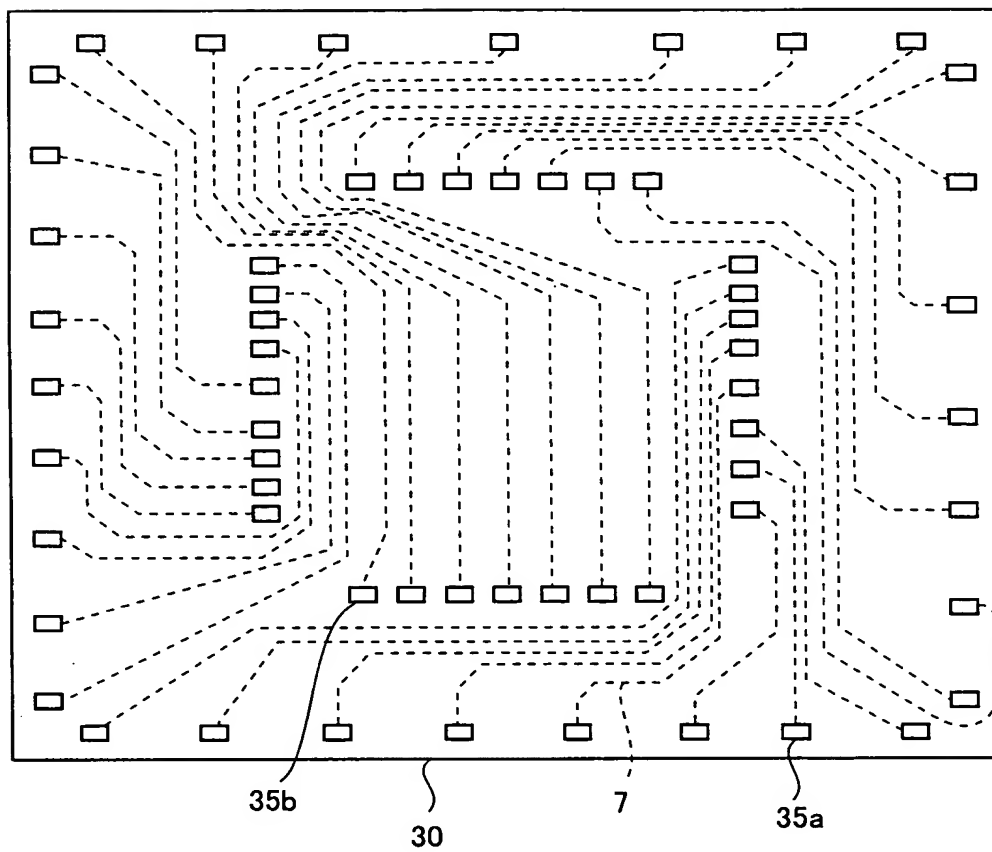




FIG. 4



[illegible]

FIG. 6

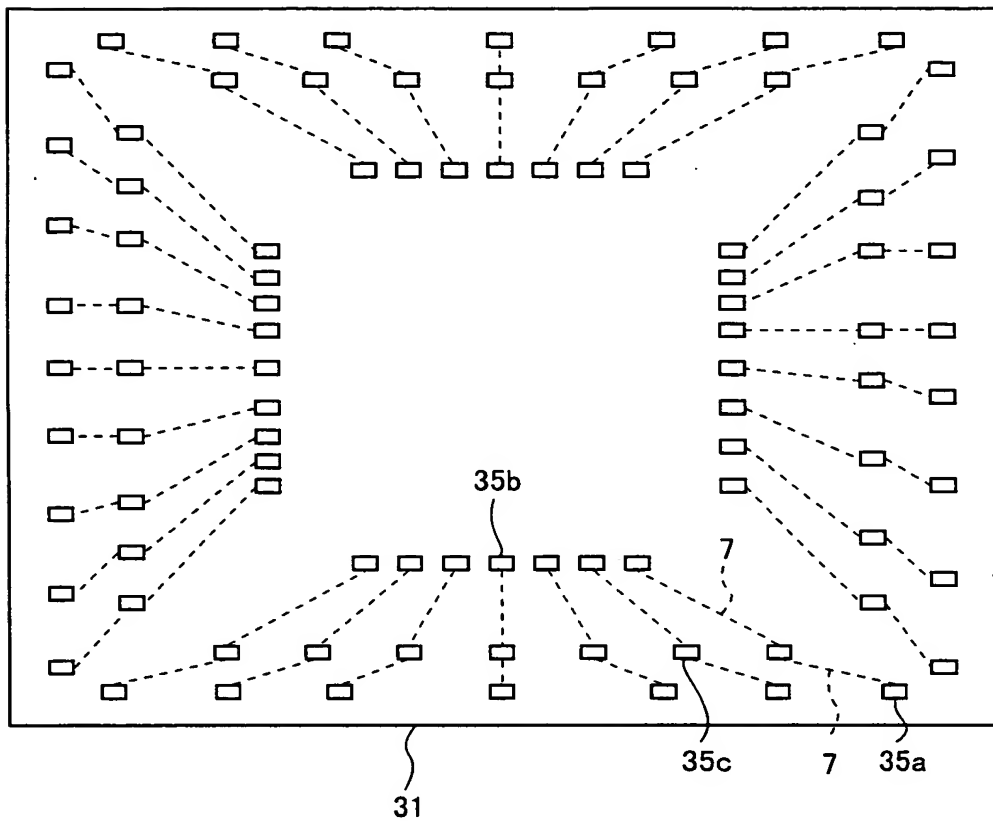


FIG. 7

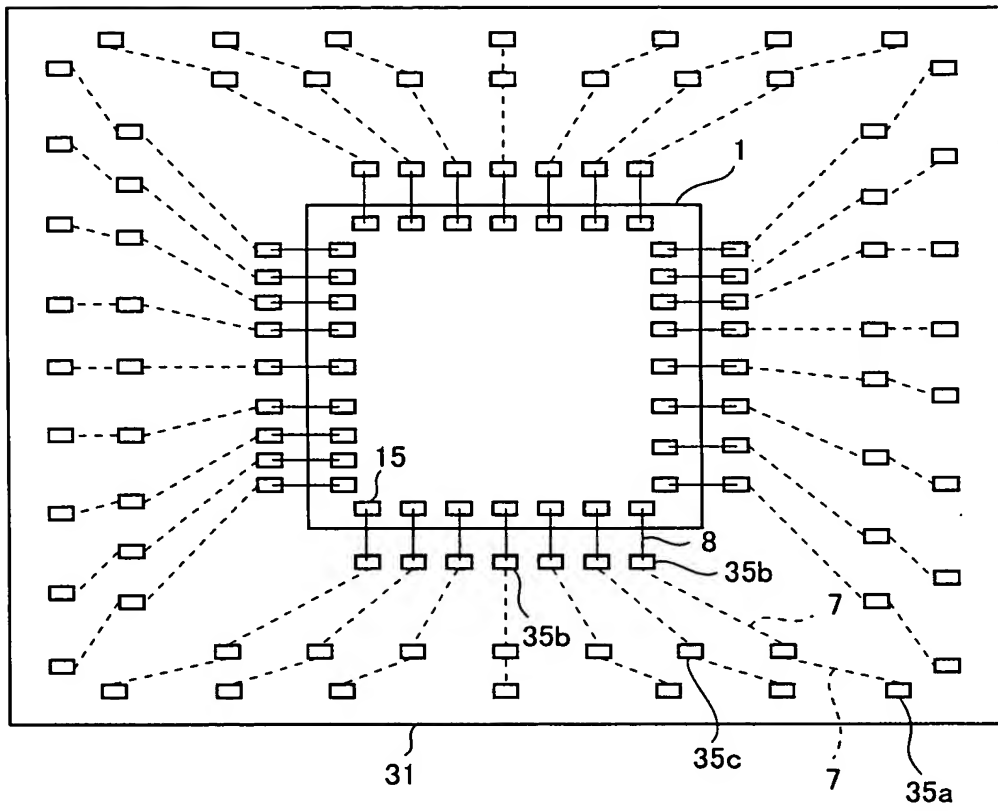


FIG. 8

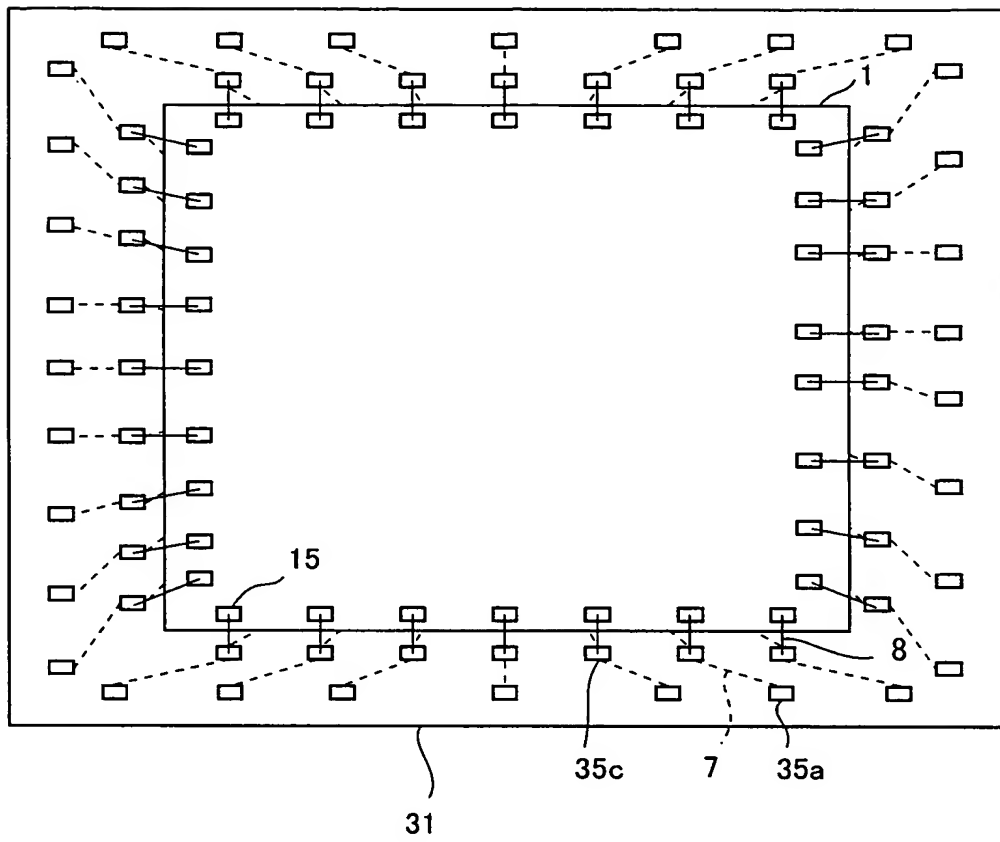




FIG. 9 (a)

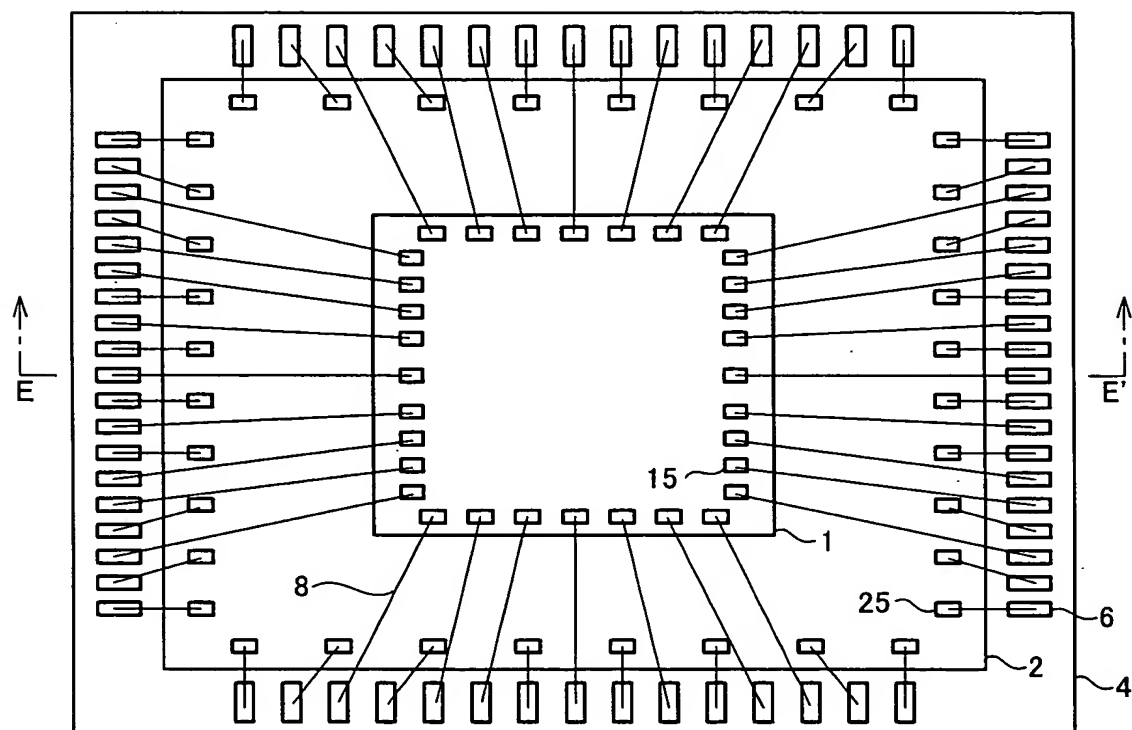


FIG. 9 (b)

